



RF360
Europe GmbH

Data sheet

SAW 2in1 Rx input diplex filter

Automotive telematics
LTE bands 25 & 66

Series/type: B4387
Ordering code: B39222B4387P810

Date: February 01, 2019
Version: 2.2

DCN: 80-PA243-314 Rev. A

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1 Application

- Low-loss 2in1 RF filter for LTE Band 25 and Band 66 systems, receive path (RX)
- Usable pass band:
Band 25: 65 MHz
Band 66: 90 MHz

2 Features

- Package size $1.5 \pm 0.1 \text{ mm} \times 1.1 \pm 0.1 \text{ mm}$
- Package height 0.45 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family
(Grade 1: $-40 \text{ }^{\circ}\text{C}$ to $+125 \text{ }^{\circ}\text{C}$)

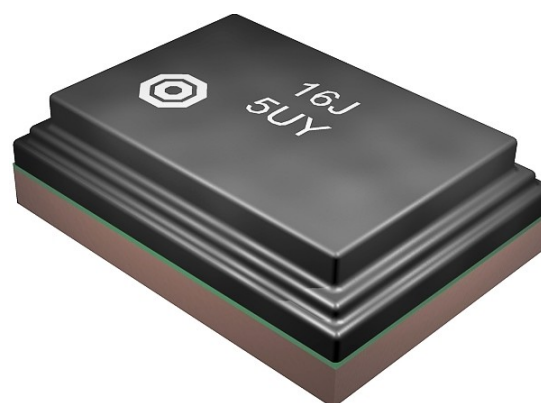
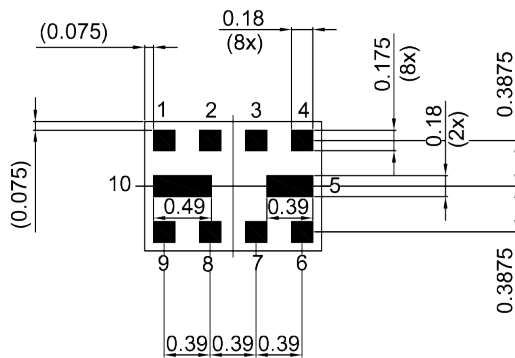


Figure 1: Picture of component with example of product marking.

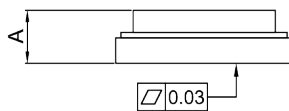
3 Package

BOTTOM VIEW

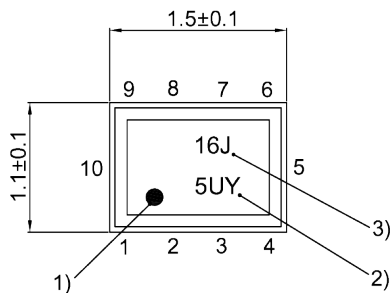


Pad and pitch tolerance ± 0.05

SIDE VIEW

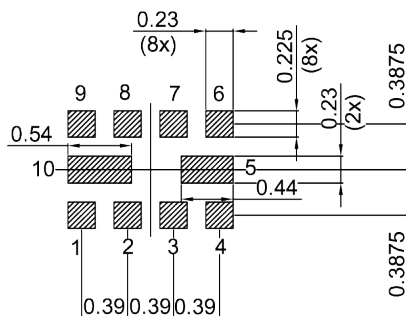


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW



Landing pad tolerance -0.02

4 Pin configuration

- 1 Input (B25 & B66)
- 6 Output (B66)
- 9 Output (B25)
- 2, 3, 4, 5, 7, 8, 10 Ground

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 20).

5 Matching circuit

■ $L_{p1} = 2.5 \text{ nH}$

■ $L_{s9} = 3.0 \text{ nH}$

■ $L_{s6} = 2.7 \text{ nH}$

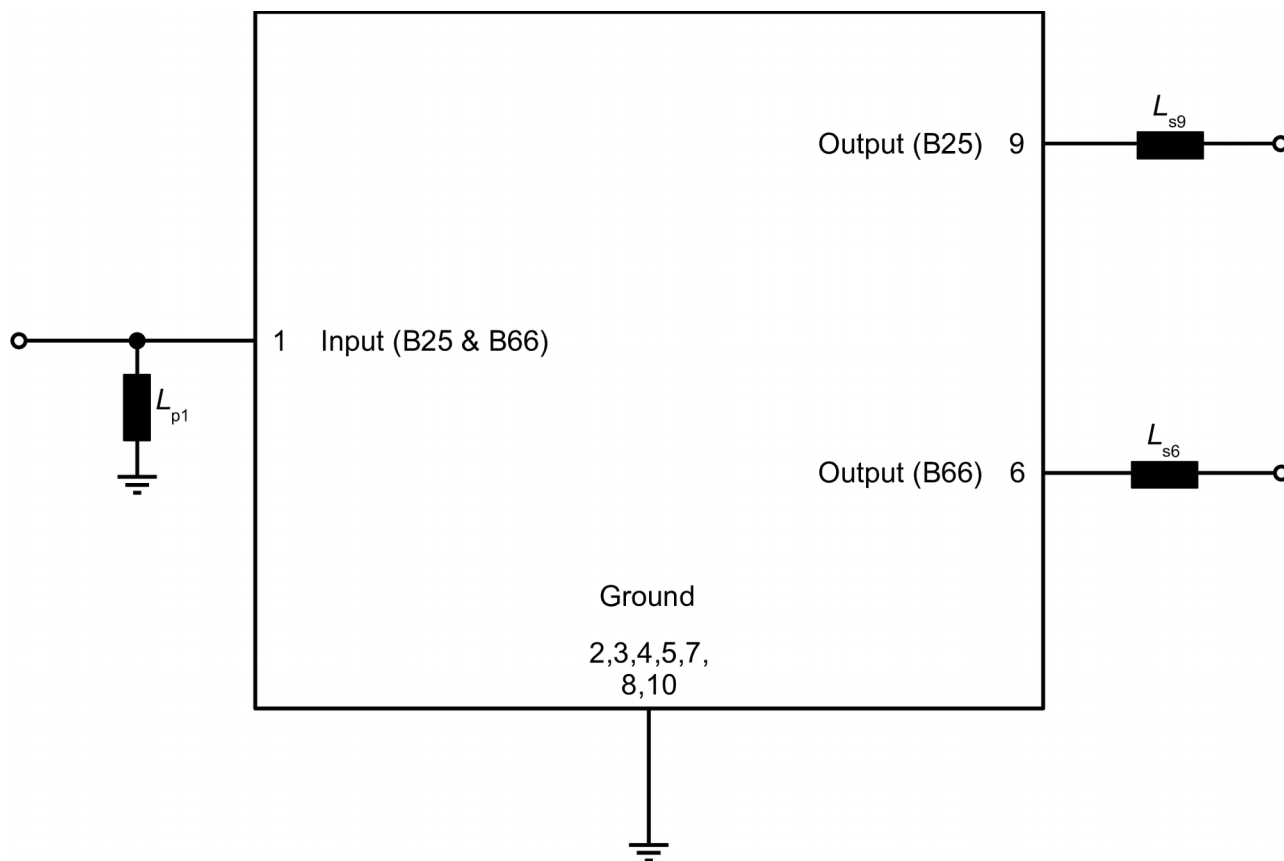


Figure 3: Schematic of matching circuit.

6 Characteristics LTE B25

Temperature range for specification
Input terminating impedance
B25 output terminating impedance
B66 output terminating impedance

T_{SPEC} = -40 °C ... +85 °C
 Z_{IN} = 50 Ω // 2.5 nH¹⁾
 $Z_{\text{B25 OUT}}$ = 50 Ω + 3.0 nH¹⁾
 $Z_{\text{B66 OUT}}$ = 50 Ω + 2.7 nH¹⁾

Characteristics LTE B25			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency		f_c	—	1962.5	—	MHz
Maximum insertion attenuation		α_{max}				
	1930.24... 1994.76 MHz		—	2.2	3.8	dB
Amplitude ripple (p-p)		$\Delta\alpha$				
	1930.24... 1994.76 MHz		—	0.8	2.6	dB
Maximum VSWR		VSWR_{max}				
@ input port	1930.24... 1994.76 MHz		—	1.5	2.0	
@ B25 output port	1930.24... 1994.76 MHz		—	1.5	2.0	
Minimum attenuation		α_{min}				
	10... 716 MHz		51	56	—	dB
	716... 814 MHz		50	55	—	dB
	814... 849 MHz		48	53	—	dB
	849... 1710 MHz		40	46	—	dB
	1710.24... 1779.76 MHz		40	47	—	dB
	1780... 1850 MHz		36	40	—	dB
	1850.24... 1909.76 MHz		31	36	—	dB
	1910.24... 1914.76 MHz		14	35	—	dB
	2055... 2110 MHz		33	36	—	dB
	2110... 3000 MHz		37	40	—	dB
	3000... 5600 MHz		35	38	—	dB
	5600... 6000 MHz		35	39	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

7 Characteristics LTE B66

Temperature range for specification	T_{SPEC}	= -40 °C ... +85 °C
Input terminating impedance	Z_{IN}	= 50 Ω // 2.5 nH ¹⁾
B25 output terminating impedance	$Z_{\text{B25 OUT}}$	= 50 Ω + 3.0 nH ¹⁾
B66 output terminating impedance	$Z_{\text{B66 OUT}}$	= 50 Ω + 2.7 nH ¹⁾

Characteristics LTE B66			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency		f_{C}	—	2155	—	MHz
Maximum insertion attenuation		α_{max}				
	2110.24... 2199.76	MHz	—	2.3	3.3	dB
Amplitude ripple (p-p)		$\Delta\alpha$				
	2110.24... 2199.76	MHz	—	0.7	2.0	dB
Maximum VSWR		VSWR_{max}				
@ input port	2110.24... 2199.76	MHz	—	1.5	2.0	
@ B66 output port	2110.24... 2199.76	MHz	—	1.5	2.0	
Minimum attenuation		α_{min}				
	10... 716	MHz	56	65	—	dB
	716... 814	MHz	54	62	—	dB
	814... 880	MHz	53	61	—	dB
	880... 915	MHz	52	59	—	dB
	915... 1500	MHz	40	51	—	dB
	1500... 1710	MHz	30	44	—	dB
	1710... 1850	MHz	40	47	—	dB
	1850.24... 1914.76	MHz	44	53	—	dB
	1915... 1980	MHz	40	45	—	dB
	1980... 2015	MHz	43	47	—	dB
	2015... 2025	MHz	40	53	—	dB
	2025... 2050	MHz	32	39	—	dB
	2050... 2075	MHz	20	33	—	dB
	2230... 2285	MHz	12	25	—	dB
	2285... 3200	MHz	32	37	—	dB
	3200... 6130	MHz	41	51	—	dB
	6130... 6600	MHz	35	50	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

8 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +125\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +125\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V}$	
Input power	P_{IN}	
@ input port: 1710.24 ... 1779.76 MHz	15 dBm	Continuous wave for 2000 h @ 55 °C.
@ input port: 1850.24 ... 1914.76 MHz	15 dBm	Continuous wave for 2000 h @ 55 °C.
@ input port: 1920.34 ... 1979.66 MHz	15 dBm	Continuous wave for 2000 h @ 55 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

9 Transmission coefficient LTE B25

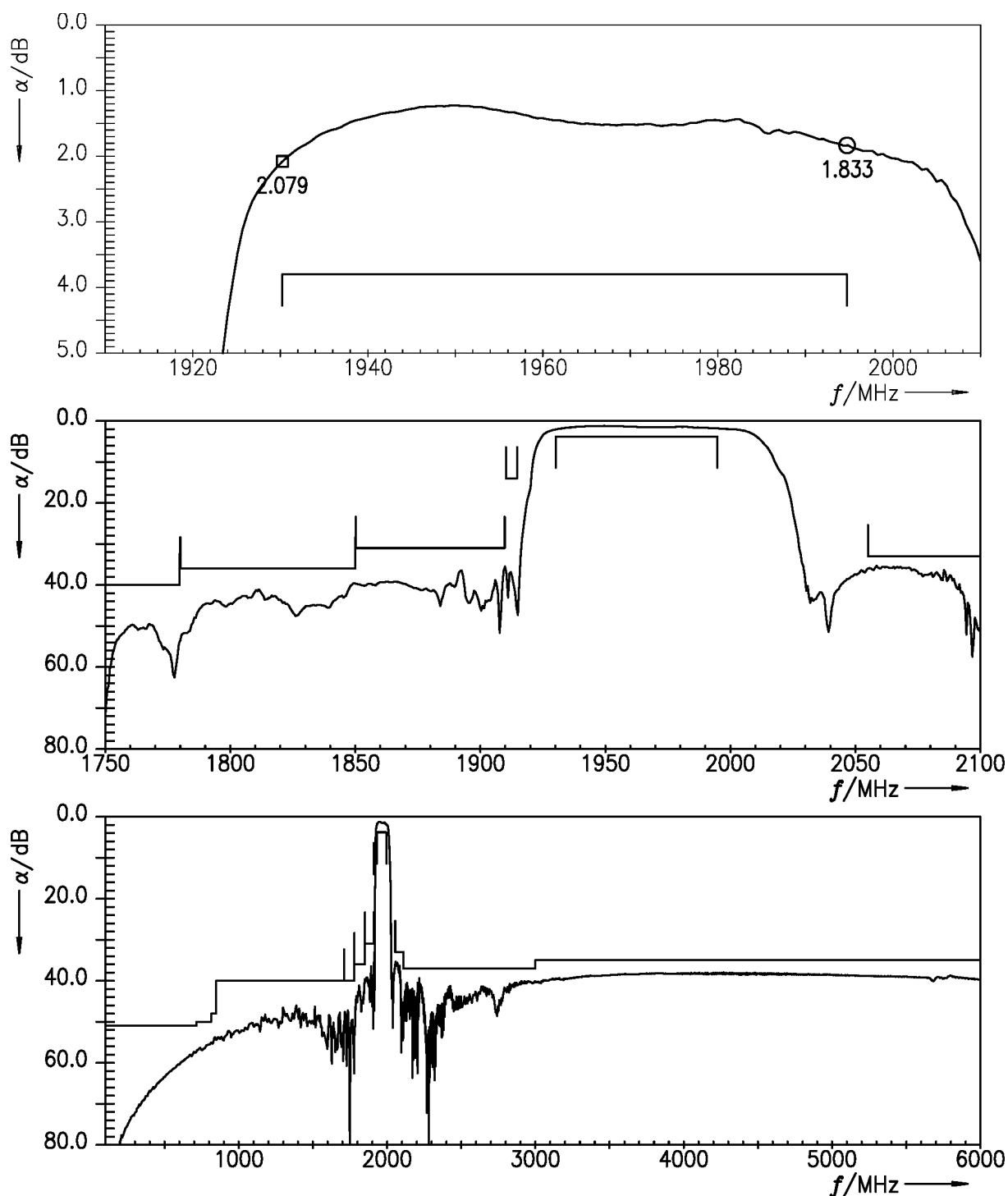


Figure 4: Attenuation LTE B25.

10 Reflection coefficients LTE B25

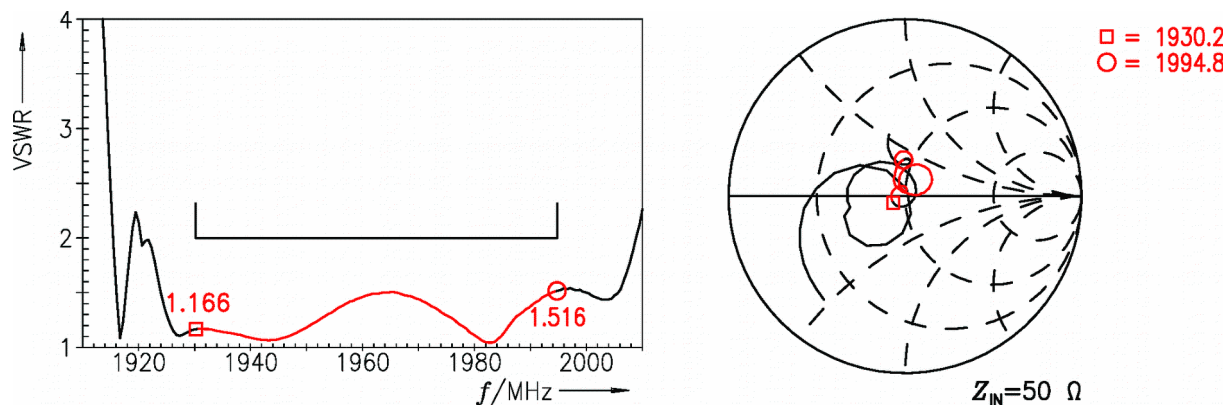


Figure 5: Reflection coefficient at input port.

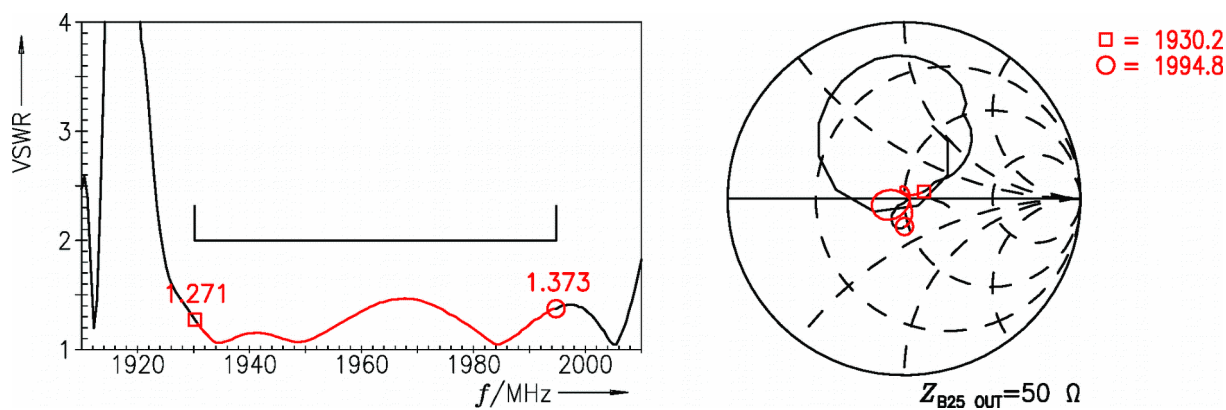


Figure 6: Reflection coefficient at B25 OUT port.

11 Transmission coefficient LTE B66

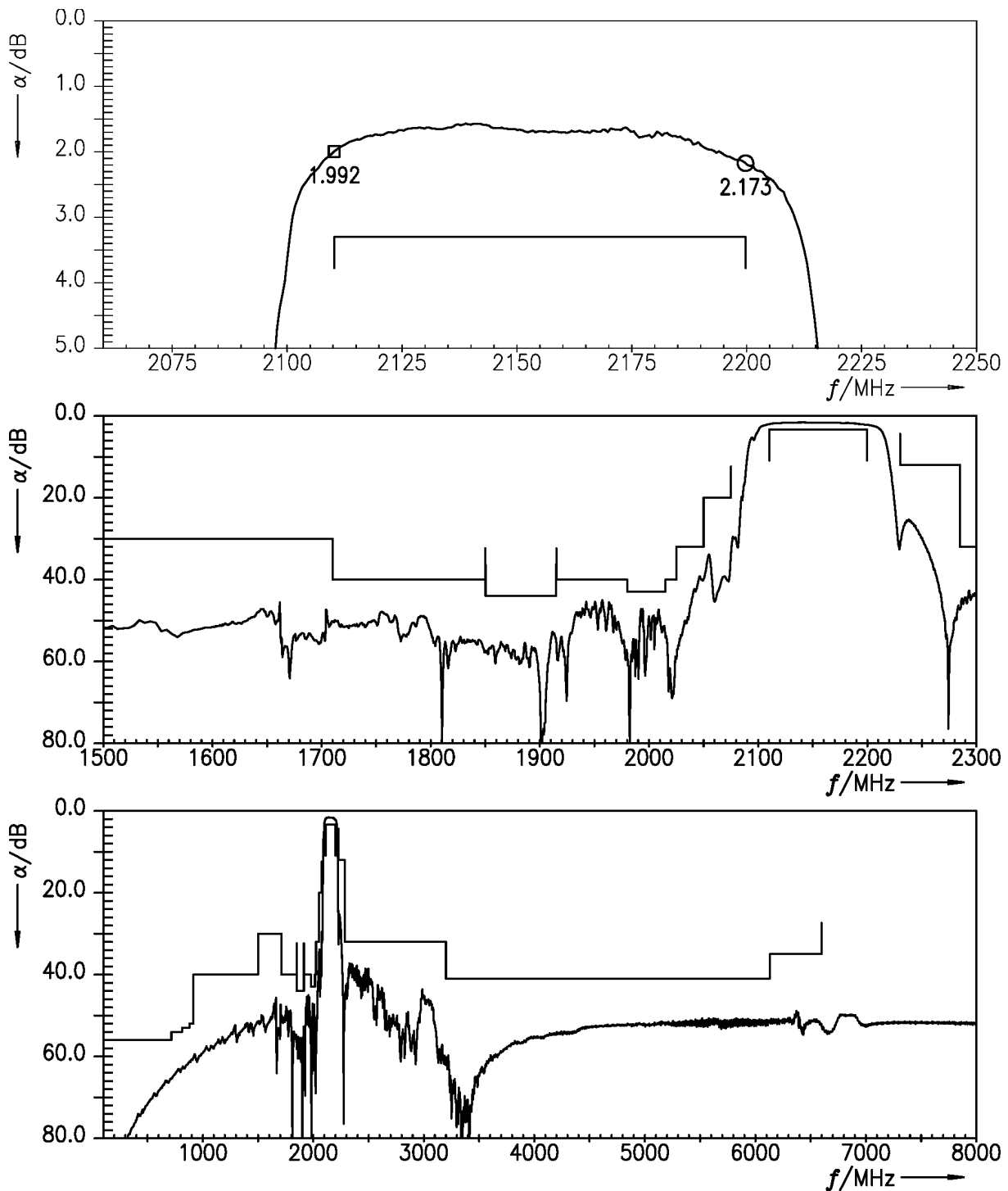


Figure 7: Attenuation LTE B66.

12 Reflection coefficients LTE B66

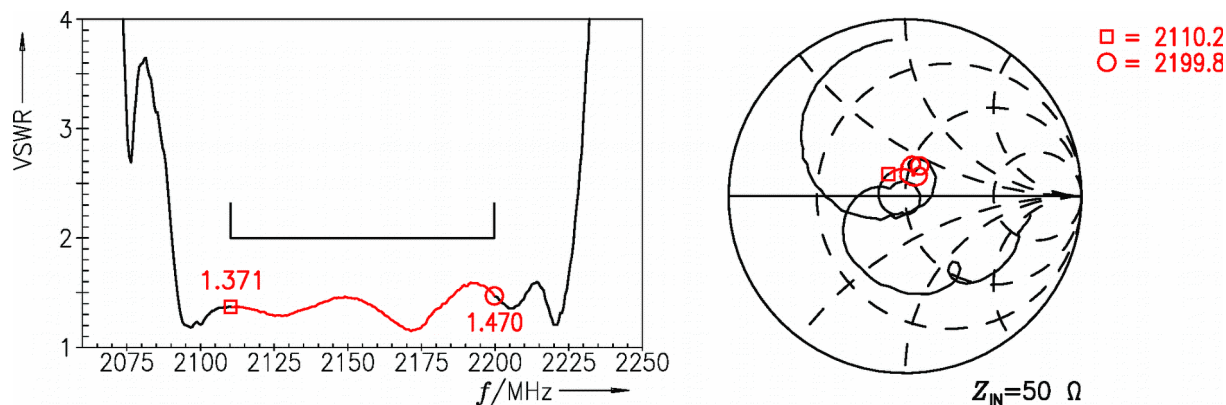


Figure 8: Reflection coefficient at input port.

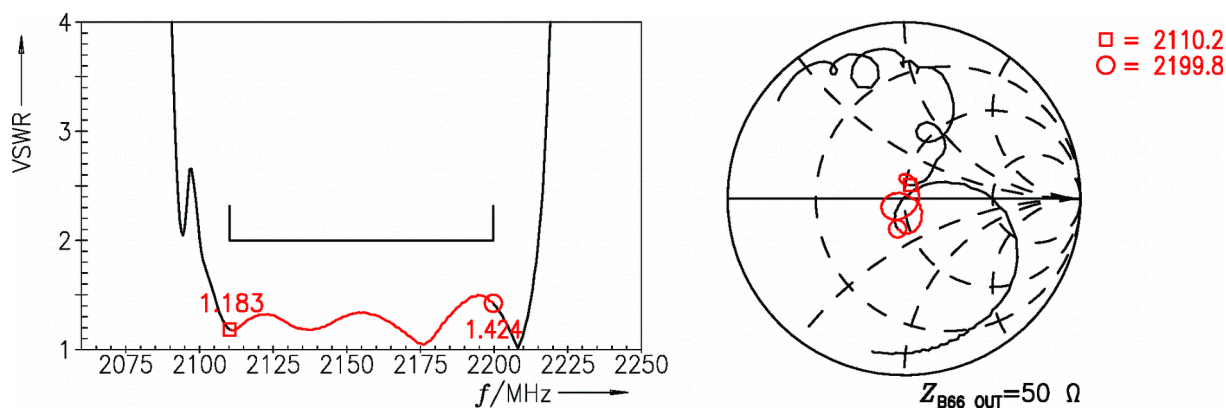


Figure 9: Reflection coefficient at B66 OUT port.

13 Packing material

13.1 Tape

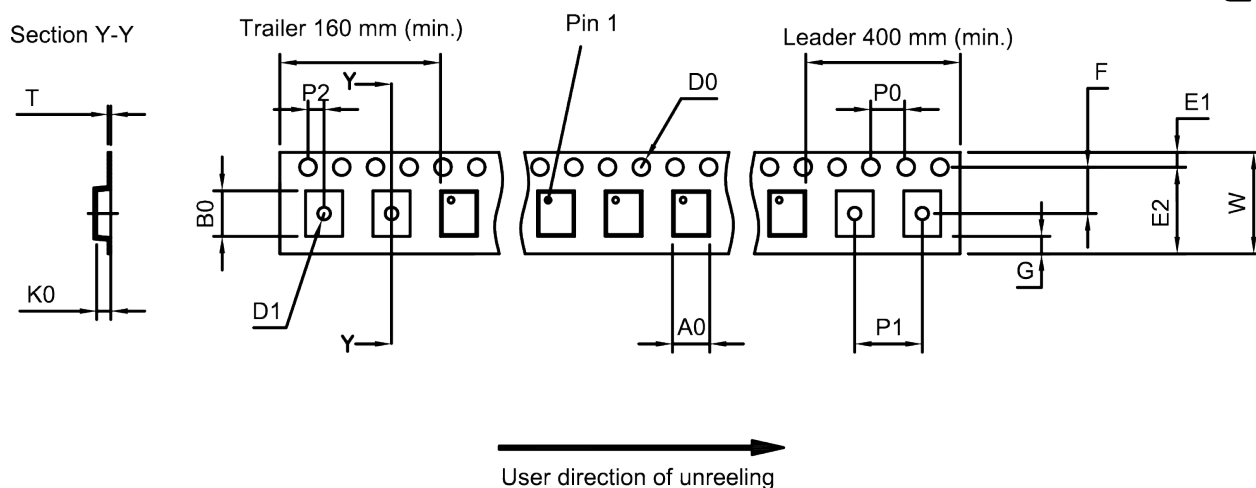


Figure 10: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.27±0.05 mm
B ₀	1.67±0.05 mm
D ₀	1.5+0.1/-0 mm
D ₁	0.5+0.1/-0 mm
E ₁	1.75±0.1 mm

E ₂	6.25 mm (min.)
F	3.5±0.05 mm
G	0.75 mm (min.)
K ₀	0.55±0.05 mm
P ₀	4.0±0.1 mm

P ₁	4.0±0.1 mm
P ₂	2.0±0.05 mm
T	0.25±0.03 mm
W	8.0+0.3/-0.1 mm

Table 1: Tape dimensions.

13.2 Reel with diameter of 180 mm

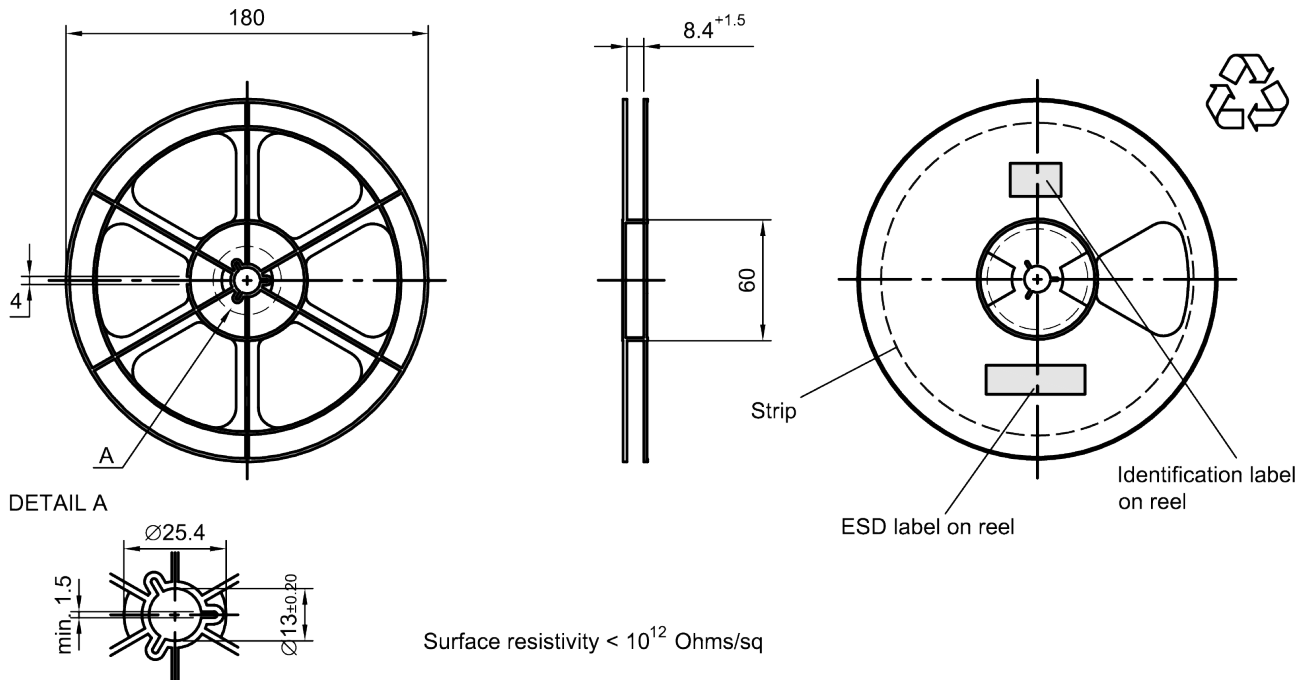


Figure 11: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

Printing
on vacuumbag

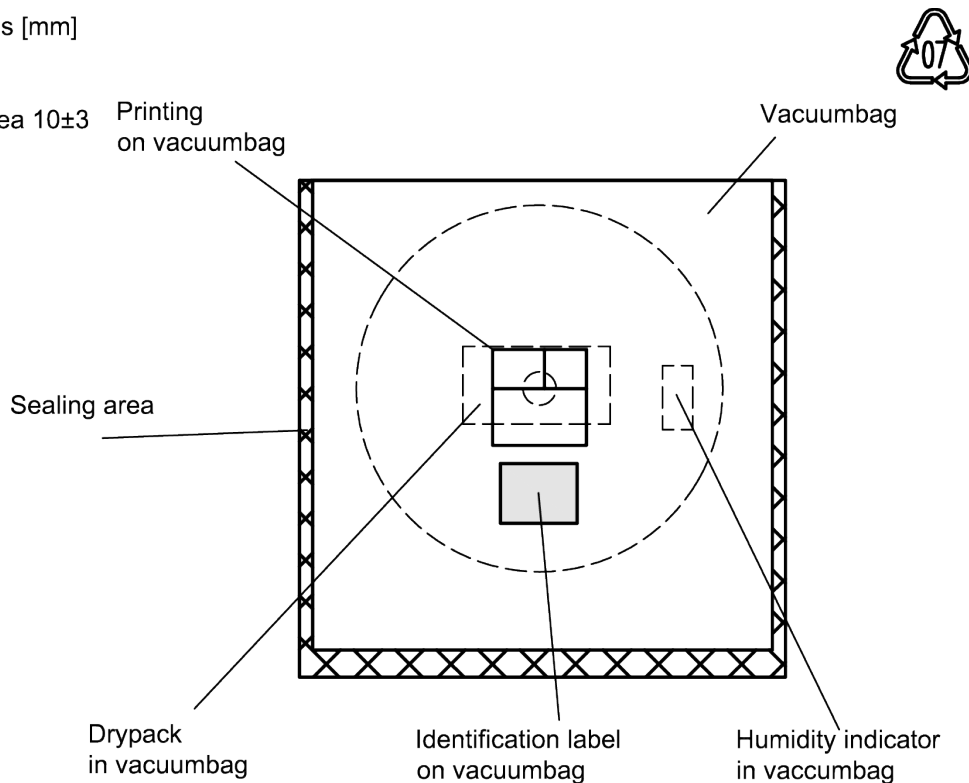


Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

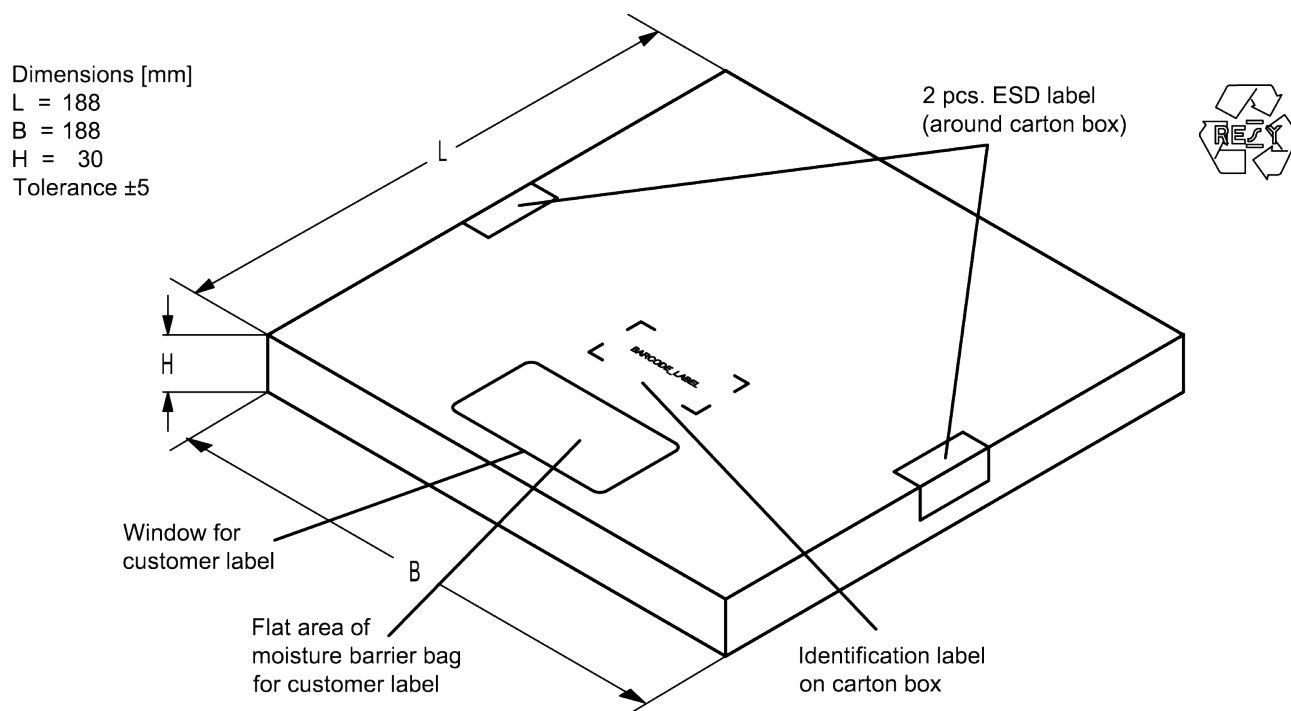


Figure 13: Drawing of folding box for reel with diameter of 180 mm.

14 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J	=>	1234
$1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0$	=	1234

The BASE32 code for product type B4387 is 493.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY	=>	12345
$5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0$	=	12345

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

15 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220\text{ °C}$	30 s to 70 s
$T > 230\text{ °C}$	min. 10 s
$T > 245\text{ °C}$	max. 20 s
$T \geq 255\text{ °C}$	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

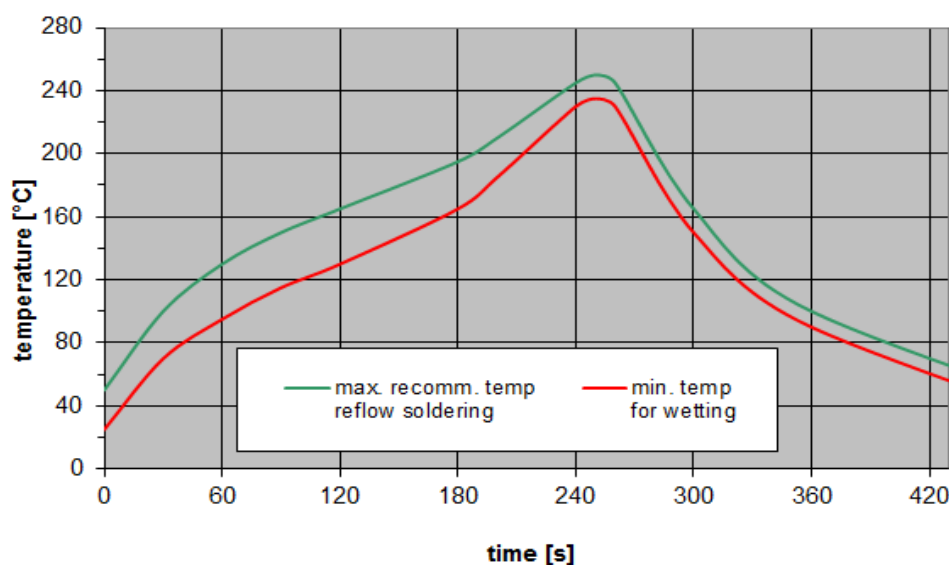


Figure 14: Recommended reflow profile for convection and infrared soldering – lead-free solder.

16 Annotations

16.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

16.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

17 Cautions and warnings**17.1 Display of ordering codes for RF360 products**

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

17.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

17.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

17.4 Package information**Landing area**

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

18 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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